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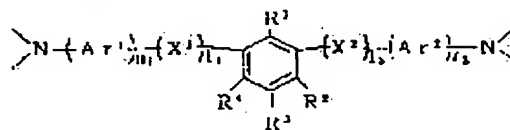
TAKEUCHI ETSU

(54) PHOTSENSITIVE RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To ensure high sensitivity and resolution and to obtain a resin layer excellent in heat resistance by incorporating a cis-diene substituted polyamic acid having a specified structure unit or a polyimide and an oxygen sensitizer.

SOLUTION: The photosensitive resin composition contains a cis-diene substituted polyamic acid having a structural unit of the formula or a polyimide and an oxygen sensitizer. In the formula, at least one of R1-R4 is a monovalent organic group having a cis-diene structure, the remainders are each H, hydroxy, carboxyl, a 1-20C alkyl or a 1-20C alkoxy, X1 and X2 are each O, S, a 1-4C alkylene or a 1-4C alkyleneoxy, Ar1 and Ar2 are each a divalent aromatic group, l1, l2, m1 and m2 are each 0 or 1, where when l1 is 1, m1 is also 1, and when l2 is 1, m2 is also 1.



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